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January 2008

74LVT240, 74LVTH240 Low Voltage Octal Buffer/Line Driver with 3-STATE Outputs

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH240), also available without bushold feature (74LVT240)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32mA/+64mA
- Functionally compatible with the 74 series 240
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human-body model > 2000V
 - Machine model > 200V
 - Charged-device model > 1000V

General Description

The LVT240 and LVTH240 are inverting octal buffers and line drivers designed to be erroved as memory address drivers, clock drivers arous conted transmitters or receivers which provide improvide PC board density.

The LVTH240 dat inp.clude bushold, aliminating the need for extern pul o sistors to hold unused inputs.

The plocts buffs or line drivers are designed for low-rolts. The VCC applications, but with the capability to vious Tile werface to a 5V environment. The LVT240 are LV. 1240 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

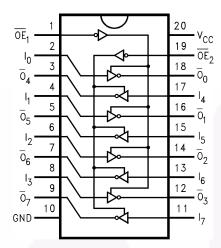
Ordering Informa on

| Order N. hber | Ckaye N mber | Fackage Description |
|---------------|-----------------|---|
| VIZ W. | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 7 VT24 J | M205 | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74L JMSA | idSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LVT240MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm |
| 74LV 7/1240WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVTH240SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVTH240MSA | MSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LVTH240MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

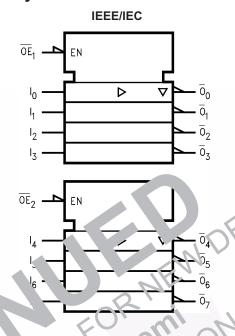
Connection Diagrams



Pin Descriptions

| Pin Names | Description |
|---------------------------------------|------------------------------|
| \overline{OE}_1 , \overline{OE}_2 | 3-STATE Output Enable Inputs |
| I ₀ –I ₇ | Inputs |
| $\overline{O}_0 - \overline{O}_7$ | 3-STATE Outputs |

Logic Symbols



Tru'n Tables

| \overline{OE}_1 I_n | Outputs (Pins 12, 14, 16, 18) |
|-------------------------|----------------------------------|
| 14, 10 16 | Н |
| L | L |
| Н | Z |

| ١ | Inp | uts | Outputs |
|---|-----------------|----------------|-------------------|
| | ŌE ₂ | I _n | (Pins 3, 5, 7, 9) |
| | L | L | Н |
| | L | Н | L |
| | Н | X | Z |

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|------------------|---|--------------------|
| V _{CC} | Supply Voltage | -0.5V to +4.6V |
| VI | DC Input Voltage | -0.5V to +7.0V |
| Vo | DC Output Voltage | |
| | Output in 3-STATE | -0.5V to +7.0V |
| | Output in HIGH or LOW State ⁽¹⁾ | -0.5V to +7.0V |
| I _{IK} | DC Input Diode Current, V _I < GND | -50mA |
| I _{OK} | DC Output Diode Current, V _O < GND | -50mA |
| Io | DC Output Current, V _O > V _{CC} | |
| | Output at HIGH State | 64mA |
| | Output at LOW State | 128mA |
| I _{CC} | DC Supply Current per Supply Pin | ±64mA |
| I _{GND} | DC Ground Current per Ground Pin | ±128mA |
| T _{STG} | Storage Temperature | -65° C tc → 150° C |

Note:

1. In Absolute Maximum Rating must be of red.

Recommended Operation Corditions

The Recommended Oproving Conditions able defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend excretely a more signing to assolute maximum ratings.

| Symb | Paraniever | Min | Max | Units |
|----------------|---|-----|-----|-------|
| | Single oltage | 2.7 | 3.6 | V |
| V _I | nput Voltage | 0 | 5.5 | V |
| IOH | HIGH-Level Output Current | | -32 | mA |
| JL | LOW-Level Output Current | | 64 | mA |
| TA | T _A Free-Air Cperating Temperature | | 85 | °C |
| Δ+/ \V | Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V |

DC Electrical Characteristics

| | | | V _{CC} | T A =- | T _A =-40°C to +85°C | | |
|--------------------------|---|---------|--|----------------------|--------------------------------|------------|-------|
| Symbol | Parameter | (V) | Conditions | Min. | Typ. ⁽²⁾ | Max. | Units |
| V _{IK} | Input Clamp Diode Voltage | 2.7 | I _I = -18mA | | | -1.2 | V |
| V _{IH} | Input HIGH Voltage | 2.7–3.6 | $V_0 \le 0.1V$ or | 2.0 | | | V |
| V _{IL} | Input LOW Voltage | 2.7–3.6 | $V_O \ge V_{CC} - 0.1V$ | | | 0.8 | V |
| V _{OH} | Output HIGH Voltage | 2.7–3.6 | $I_{OH} = -100 \mu A$ | V _{CC} -0.2 | | | V |
| | | 2.7 | $I_{OH} = -8mA$ | 2.4 | | | 1 |
| | | 3.0 | $I_{OH} = -32mA$ | 2.0 | | | 1 |
| V _{OL} | Output LOW Voltage | 2.7 | $I_{OL} = 100 \mu A$ | | | 0.2 | V |
| | | | I _{OL} = 24mA | | | 0.5 | |
| | | 3.0 | I _{OL} = 16mA | | | 0.4 | 5 |
| | | | $I_{OL} = 32mA$ | | | 0.5 | |
| | | | I _{OL} = 64mA | | | 0.55 | 1 |
| I _{I(HOLD)} (3) | Bushold Input Minimum | 3.0 | V _I = 0.8V | 75 | | 1 | μA |
| | Drive | | V _I = 2.0V | -75 | An | | 1 |
| I _{I(OD)} (3) | Bushold Input Over-Drive | 3.0 | (4) | 500 | | | μA |
| | Current to Change State | | | -5υύ | OU. | | 14 |
| I | Input Current | 3.5 | \ -5.5V | | 5 | 10 | μA |
| | Control Pins | 3.0 | V _I = V or V _{CC} | 0/ | - 1/2 | ±1 | |
| | Data Pins | | V _I = 0V | (_ (| 5/1/ | – 5 | |
| | | | $V_1 = V_{CC}$ | 2.0 | | 1 | |
| I _{OFF} | Power Off Leakage Irrent | U | $vV \le V_1 \text{ or } V_0 \le 5.5V$ | 71 | | ±100 | μA |
| I _{PU/PD} | Power up/ Jwn 3-ST/ | 0-1.5V | $V_0 = 0.5V \text{ to } 3.0V,$ | | | ±100 | μA |
| | Output C rent | | $V_1 = CND \text{ or } V_{CC}$ | | | | |
| I _{OZL} | STATE O akage | 3.6 | V _O = 0.5V | | | – 5 | μA |
| - 4 | 3-STATE Jutput Leakage | 3.6 | 'V _C = 3.0V | | | 5 | μA |
| | Current | 9.0 | VO - 0.0V | | |] | μΛ |
| I _{OZH} + | 3-STATE Oviput Leakage | 3.6 | $V_{CC} < V_O \le 5.5V$ | | | 10 | μA |
| | Current | 16 | | | | | |
| Іссн | Power Supply Current | 3.6 | Outputs HIGH | | | 0.19 | mA |
| lecr | Power Supply Cur ent | 3.6 | Outputs LOW | | | 5 | mA |
| ICCZ | Power Suprly Current | 3.6 | Outputs Disabled | | | 0.19 | mA |
| I _{CCZ} + | Power Supply Current | 3.6 | $V_{CC} \le V_O \le 5.5V$, | | | 0.19 | mA |
| | | | Outputs Disabled | | | | |
| Δl _{CC} | Increase in Power Supply Current ⁽⁶⁾ | 3.6 | One Input at V _{CC} – 0.6V, Other Inputs at V _{CC} or | | | 0.2 | mA |
| | Guilett. | | GND | | | | |

Notes:

- 2. All typical values are at $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$.
- 3. Applies to bushold versions only (74LVTH240).
- 4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- 6. This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics⁽⁷⁾

| | | | Conditions | T _A = 25°C | | | |
|------------------|---|---------------------|---------------------------------|-----------------------|------|------|-------|
| Symbol | Parameter | V _{CC} (V) | $C_L = 50 pF, R_L = 500 \Omega$ | Min. | Тур. | Max. | Units |
| V _{OLP} | Quiet Output Maximum Dynamic V _{OL} | 3.3 | (8) | | 0.8 | | V |
| V _{OLV} | Quiet Output Minimum Dynamic V _{OL} | 3.3 | (8) | | -0.8 | | V |

Notes:

- 7. Characterized in SOIC package. Guaranteed parameter, but not tested.
- 8. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

| | | $T_A = -40^{\circ} to C$ $C_L = 50pF, = 10^{\circ}$ | |
|---------------------------------------|-----------------------------------|---|----|
| | | $V_{CC} = 3. \ \ \forall \pm \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$ | |
| Symbol | Parameter | Min. Win. Max. Unit | :s |
| t _{PLH} | Propagation Delay, Data to Output | 1.1 3.8 1.1 1.6 ns | |
| t _{PHL} | | 1.3 4.2 | |
| t _{PZH} | Output Enable Time | 1 4.6 1.1 5.6 ns | |
| t _{PZL} | | 1 4.4 1.4 5.1 | |
| t _{PHZ} | Output Disable Tim | 2.0 4.5 2.0 4.7 ns | |
| t _{PLZ} | | 1.8 4.3 | |
| t _{OSHL} , t _{OSLH} | Output tr Ju., Jut & w(10) | 1.0 1.0 ns | |

Notes:

- 9. All typical values are $\sim 3.3 \text{V}$ T_A = 25°C.
- 10. Skew de. as absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, of the same direction, or LOW-to-HIGH (too-H).

Cap Litance(11)

| Symbol | Pararieter | Conditions | Typical | Units |
|------------------|--------------------|--|---------|-------|
| C _{IN} | Input Capacitance | $V_{CC} = 0V$, $V_I = 0V$ or V_{CC} | 3 | pF |
| C _{OUT} | Output Capacitance | $V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC} | 6 | pF |

Note:

11. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

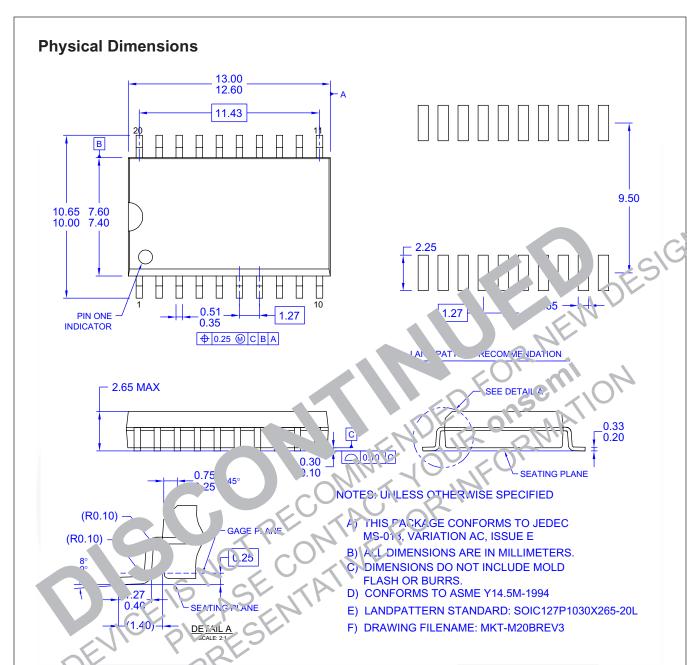


Figure 1. 20-Levi Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued) 12.6±0.10 0.40 TYP -A-20 11 12 11 5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-3.9 (2.13)△ 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT. J.6 TYP 1.27 ALL LEAD TIPS △ 0.1 C 2.1 MAX.--C-0.15 - 0.255.35-0.51 1.27 TYP 7° TYP ARE IN MILLIMATER GAGE PLANE 0°-8° TYP CONFORMS TO LIAU EDG-7320 REGISTRATION ESTABLISHED IN DECEMBER, 1998. D.Y.L.NSIONS ARE EXCLUSIVE OF TURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60 ± 0.15 SEATING PLANE 1.25 -DETAIL A

M20DREVC

Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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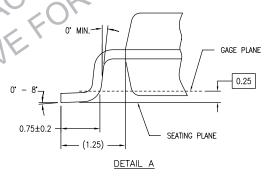
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9.12

Physical Dimensions (Continued) 7.2±0.30 0.68 TYP В 5.58 5.3±0.30 7.8 10 3.9 ○ 0.2 C A B PIN #1 IDENT. RECOMMENDATIONS △ 0.10 C ALL LEAD TIPS 1.75±u 2.0 MAX. 0.65 TYP 0.15M L

NOTES

- NFORMS TO JEDIC REGISTRATION ARIATION AC, LATE 1/94.
- DIMENSIONS ARE IN MILLINIZIERS.
- DIN'ELISIONS ARE FACLUSIVE C: DURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- CIMENSIONS AND TOLERAILC'S PER ASME Y14.5M 1994.



SA20REVB

Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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Physical Dimensions (Continued) 5.5±0.1 -A--0.20 02ا 4.16 6,4 4.4±0.1 -B-3,2 0.2 C B A 0.65 ALL LEAD PIN #1 IDENT. O.1 C 0.90 1.2 -C-0.09-0.20 0.05 0.65 -12.00° GAGE PLANE

NO S.

A. CONFORMS TO JEDEC RESISTRATION MIL-133 VARIATION ACRES NOT. 6, DATE $7/93.\,$

P. D'MENSIONS ARE IN MILLIMETERS.

- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONS AND TO ERANCES PER ANSI Y14.5M, 1982.

8°7 -0.6±0.1--1.00 SEATING PLANE R0.09min

DETAIL A

MTC20REVD1

Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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